

# **Excellent Integrated System Limited**

Stocking Distributor

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ON Semiconductor NSR0140P2T5G

For any questions, you can email us directly: <a href="mailto:sales@integrated-circuit.com">sales@integrated-circuit.com</a>



## **NSR0140P2T5G**

# **Schottky Barrier Diode**

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

#### **Features**

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.28 V (Typ) @ I<sub>F</sub> = 1.0 mA
- Low Reverse Current
- Lead-Free Plating
- This is a Pb-Free Device



#### ON Semiconductor®

http://onsemi.com

### 40 V SCHOTTKY BARRIER DIODE





#### MARKING DIAGRAM



SOD-923 CASE 514AA PLASTIC

> M = Specific Device Code\* (Character is rotated 270° clockwise)

M = Month Code■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit	
Repetitive Peak Reverse Voltage	$V_{RM}$	40	V	
Continuous Reverse Voltage (DC)	V <sub>R</sub>	30	V	
Continuous Forward Current (DC)	IF	70	mA	
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	500	mA	
ESD Rating: Class 1C per Human Body Model				

Class A per Machine Model

Stresses exceeding Maximum Ratings may damage

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	100	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	1000	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +125	°C

1. FR-5 Minimum Pad.

#### **ORDERING INFORMATION**

Device	Package	Shipping†
NSR0140P2T5G	SOD-923 (Pb-Free)	8000/Tape & Reel

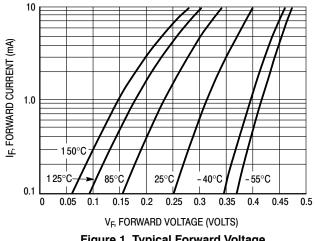
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



### **NSR0140P2T5G**

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μA)	V <sub>(BR)R</sub>	30	-	-	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	C <sub>T</sub>	-	2.0	2.5	pF
Reverse Leakage (V <sub>R</sub> = 30 V)	I <sub>R</sub>	-	300	500	nA
Forward Voltage (I <sub>F</sub> = 1.0 mA)	V <sub>F</sub>	-	0.28	0.35	V



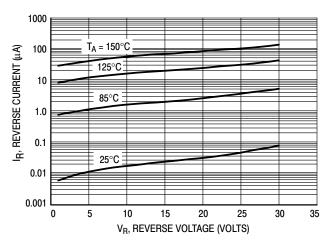


Figure 1. Typical Forward Voltage

Figure 2. Reverse Current versus Reverse Voltage

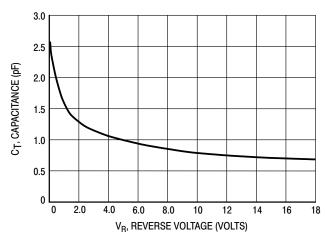


Figure 3. Typical Capacitance



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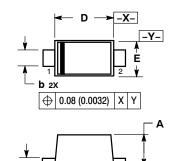
Datasheet of NSR0140P2T5G - DIODE SCHOTTKY 30V 70MA SOD923

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

#### NSR0140P2T5G

#### PACKAGE DIMENSIONS

SOD-923 CASE 514AA-01 ISSUE D



#### NOTES:

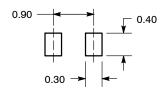
- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.34	0.39	0.43	0.013	0.015	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
Е	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

#### SOLDERING FOOTPRINT\*



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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